

1. Product profile

1.1 General description

PNP transistor in a plastic SOT23 envelope. It is primarily intended for use in RF wideband amplifiers, such as in aerial amplifiers, radar systems, oscilloscopes, spectrum analyzers, etc. The transistor features low intermodulation distortion and high power gain; due to its very high transition frequency, it also has excellent wideband properties and low noise up to high frequencies. NPN complements are BFR92 and BFR92A.

1.2 Features and benefits

- High power gain
- Low intermodulation distortion

1.3 Applications

- Oscilloscopes and spectrum analyzers
- Radar systems
- RF wideband amplifiers

1.4 Quick reference data

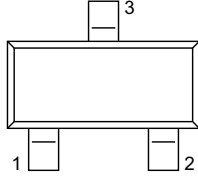
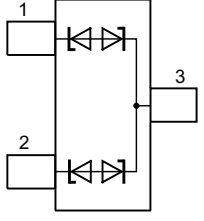
Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{CBO}	collector-base voltage	open emitter	-	-	-20	V
V_{CEO}	collector-emitter voltage	open base	-	-	-15	V
I_C	DC collector current		-	-	-25	mA
P_{tot}	total power dissipation	up to $T_s = 95\text{ °C}$ [1]	-	-	300	mW
f_T	transition frequency	$I_C = -14\text{ mA}$; $V_{CE} = -10\text{ V}$; $f = 500\text{ MHz}$	-	5	-	GHz
C_{re}	feedback capacitance	$I_C = -2\text{ mA}$; $V_{CE} = -10\text{ V}$; $f = 1\text{ MHz}$	-	0.7	-	pF
G_{UM}	maximum unilateral power gain	$I_C = -14\text{ mA}$; $V_{CE} = -10\text{ V}$; $f = 500\text{ MHz}$ $T_{amb} = 25\text{ °C}$	-	18	-	dB
NF	noise figure	$I_C = -5\text{ mA}$; $V_{CE} = -10\text{ V}$; $f = 500\text{ MHz}$; $T_{amb} = 25\text{ °C}$	-	2.5	-	dB
d_{im}	intermodulation distortion	$I_C = -14\text{ mA}$; $V_{CE} = -10\text{ V}$; $R_L = 75\text{ }\Omega$; $V_o = 150\text{ mV}$; $T_{amb} = 25\text{ °C}$; $f_{(p+q-r)} = 493.25\text{ MHz}$	-	-60	-	dB

[1] T_s is the temperature at the soldering point of the collector tab.

2. Pinning information

Table 2. Pinning

Pin	Description	Simplified outline	Graphic symbol
1	base		 001aaa629
2	emitter		
3	collector		

3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BFT92	TO-236AB	Plastic surface mounted package; 3 leads	SOT23

4. Marking

Table 4. Marking codes

Type number	Marking code
BFT92	W1%

5. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CBO}	collector-base voltage	open emitter	-	-20	V
V_{CEO}	collector-emitter voltage	open base	-	-15	V
V_{EBO}	emitter-base voltage	open collector	-	-2	V
I_C	DC collector current		-	-25	mA
I_{CM}	peak collector current	$f > 1$ MHz	-	-35	mA
P_{tot}	total power dissipation	up to $T_s = 95$ °C [1]	-	300	mW
T_{stg}	storage temperature		-65	150	°C
T_j	junction temperature		-	175	°C

[1] T_s is the temperature at the soldering point of the collector tab.

6. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Typ	Unit
$R_{th\ j-s}$	thermal resistance from junction to soldering point	up to $T_s = 95\text{ °C}$	[1] 260	K/W

[1] T_s is the temperature at the soldering point of the collector tab.

7. Characteristics

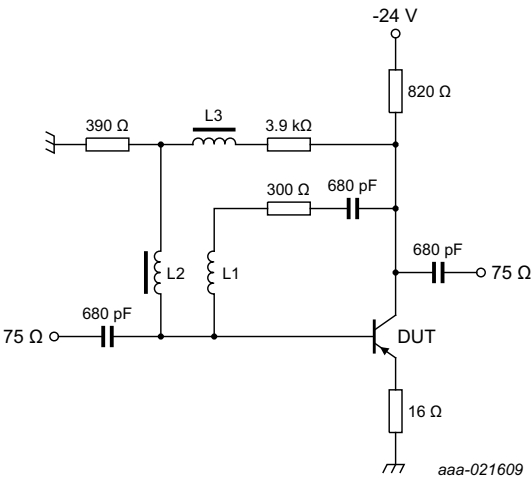
Table 7. Characteristics

$T_j = 25\text{ °C}$ unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
I_{CBO}	collector cut-off current	$I_E = 0$; $V_{CB} = -10\text{ V}$	-	-	-50	nA
h_{FE}	DC current gain	$I_C = -14\text{ mA}$; $V_{CE} = -10\text{ V}$	20	50	-	
f_T	transition frequency	$I_C = -14\text{ mA}$; $V_{CE} = -10\text{ V}$; $f = 500\text{ MHz}$	-	5	-	GHz
C_c	collector capacitance	$I_E = i_e = 0$; $V_{CB} = -10\text{ V}$; $f = 1\text{ MHz}$	-	0.75	-	pF
C_e	emitter capacitance	$I_C = i_c = 0$; $V_{EB} = -0.5\text{ V}$; $f = 1\text{ MHz}$	-	0.8	-	pF
C_{re}	feedback capacitance	$I_C = -2\text{ mA}$; $V_{CE} = -10\text{ V}$; $f = 1\text{ MHz}$	-	0.7	-	pF
G_{UM}	maximum unilateral power gain	$I_C = -14\text{ mA}$; $V_{CE} = -10\text{ V}$; $f = 500\text{ MHz}$; $T_{amb} = 25\text{ °C}$	[1] -	18	-	dB
NF	noise figure	$I_C = -5\text{ mA}$; $V_{CE} = -10\text{ V}$; $f = 500\text{ MHz}$; $T_{amb} = 25\text{ °C}$	-	2.5	-	dB
V_o	output voltage	$d_{im} = -60\text{ dB}$ (DIN 45004B); $I_C = -14\text{ mA}$; $V_{CE} = -10\text{ V}$; $R_L = 75\text{ }\Omega$; $V_p = V_o$ at $d_{im} = -60\text{ dB}$; $f_p = 495.25\text{ MHz}$; $V_q = V_o - 6\text{ dB}$; $f_q = 503.25\text{ MHz}$; $V_r = V_o - 6\text{ dB}$; $f_r = 505.25\text{ MHz}$; measured at $f_{(p+q-r)} = 493.25\text{ MHz}$.	-	150	-	mV

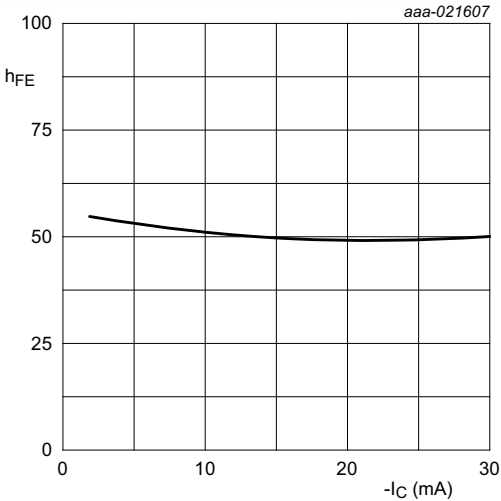
[1] G_{UM} is the maximum unilateral power gain, assuming S_{12} is zero and $G_{UM} = 10 \log \frac{|S_{21}|^2}{(1 - |S_{11}|^2)(1 - |S_{22}|^2)} \text{ dB}$

8. Graphs



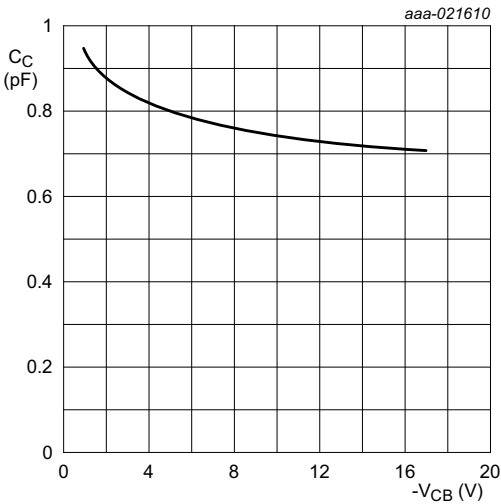
L2 = L3 = 5 uH Ferroxcube choke, catalogue number 3122 108 20150
L1 = 4 turns 0.35 mm copper wire; winding pitch 1 mm; internal diameter 4 mm

Fig 1. Intermodulation distortion test circuit



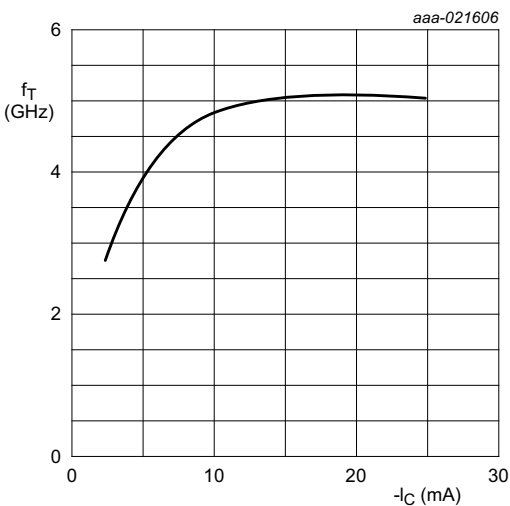
$V_{CE} = -10\text{ V}$; $T_j = 25\text{ }^\circ\text{C}$

Fig 2. DC current gain as a function of collector current



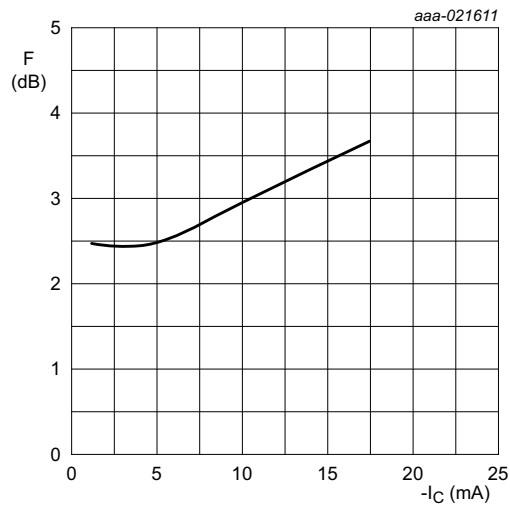
$I_E = i_e = 0$; $f = 1\text{ MHz}$; $T_j = 25\text{ }^\circ\text{C}$

Fig 3. Collector capacitance as a function of collector-base voltage



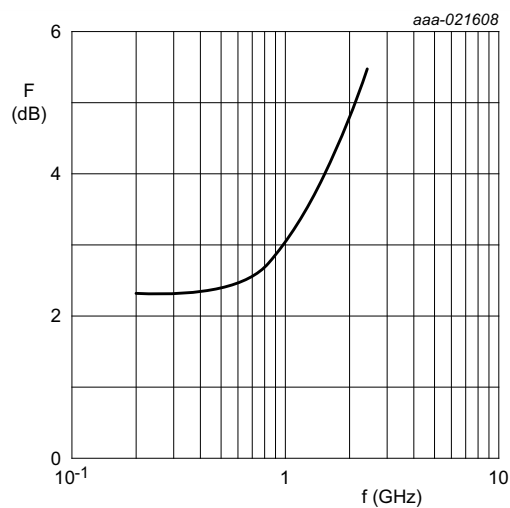
$V_{CE} = -10\text{ V}$; $f = 500\text{ MHz}$; $T_j = 25\text{ }^\circ\text{C}$

Fig 4. Transition frequency as a function of collector current



$V_{CE} = -10$ V; $Z_s = \text{opt}$; $f = 500$ MHz; $T_{\text{amb}} = 25$ °C

Fig 5. Minimum noise figure as a function of collector current.



$I_C = -2$ mA; $V_{CE} = -10$ V; $Z_s = \text{opt}$; $T_{\text{amb}} = 25$ °C

Fig 6. Minimum noise figure as a function of frequency.

9. Package outline

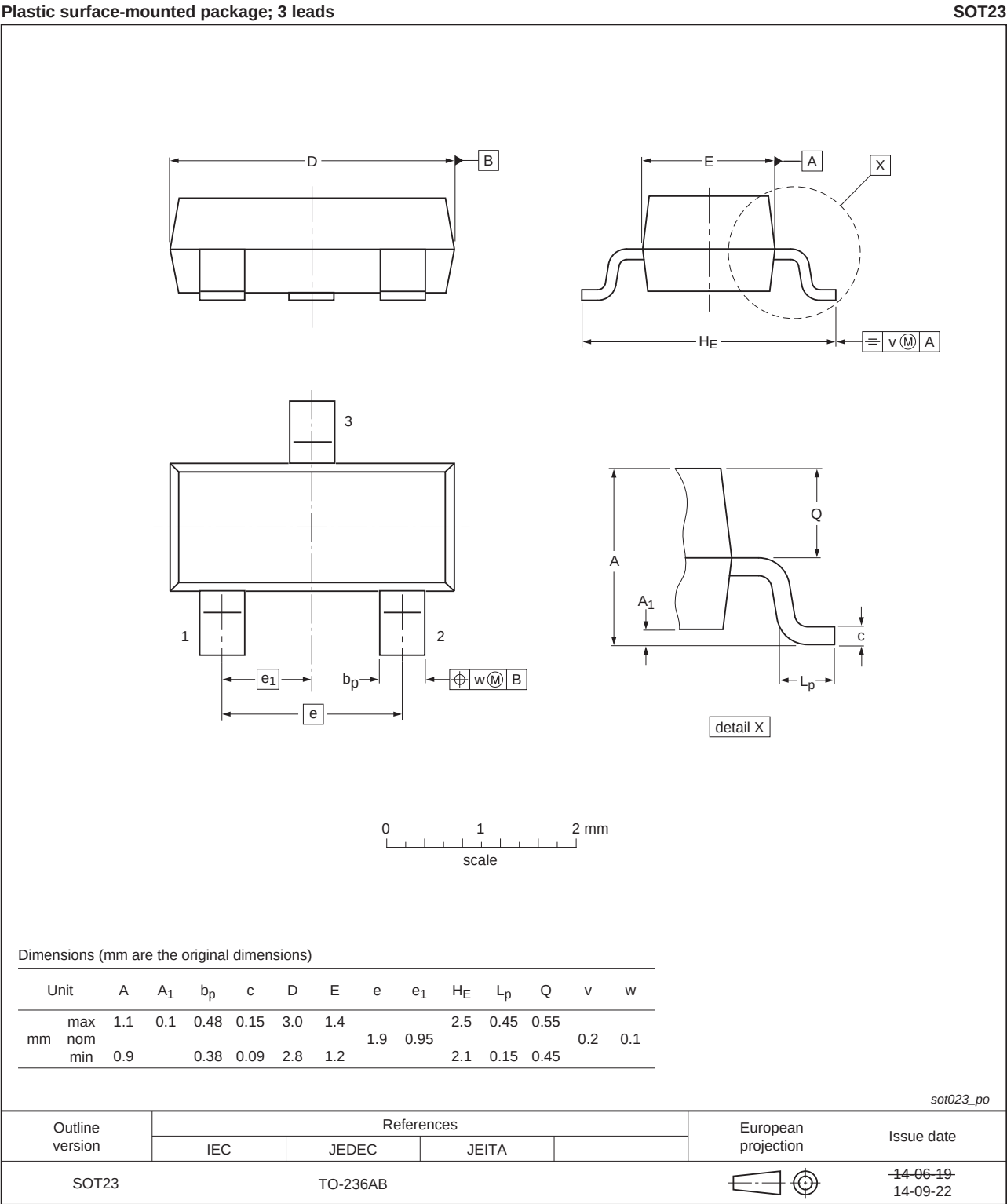


Fig 7. Package outline SOT23 (TO-236AB)

10. Revision history

Table 8. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BFT92 v.3	20160122	Product data sheet	-	BFT92 v.2
Modifications:	- The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors. - Legal texts have been adapted to the new company name where appropriate.			
BFT92 v.2	19921101	Product specification	-	-

11. Legal information

11.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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13. Contents

1 **Product profile** 1

1.1 General description 1

1.2 Features and benefits 1

1.3 Applications 1

1.4 Quick reference data 1

2 **Pinning information** 2

3 **Ordering information** 2

4 **Marking** 2

5 **Limiting values** 2

6 **Thermal characteristics** 3

7 **Characteristics** 3

8 **Graphs** 4

9 **Package outline** 6

10 **Revision history** 7

11 **Legal information** 8

11.1 Data sheet status 8

11.2 Definitions 8

11.3 Disclaimers 8

11.4 Trademarks 9

12 **Contact information** 9

13 **Contents** 10

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